

CIRCUIT BOARD PROCESSING TECHNIQUES
USING SOLDER FUSING

ABSTRACT OF THE DISCLOSURE

5 A circuit board processing system has a circuit board fabrication stage
configured to fabricate a circuit board having a set of circuit board pads, and a solder
fusing stage coupled to the circuit board fabrication stage. The solder fusing stage is
configured to (i) apply flux and solder concurrently to the set of circuit board pads, and
(ii) activate the flux and melt the solder to form a set of substantially flat solder coatings
10 which is fused to the set of circuit board pads. The circuit board processing system
further includes a washing stage coupled to the solder fusing stage. The washing stage
is configured to remove contamination from a surface of the circuit board having the
circuit board pads and from the set of substantially flat solder coatings which is fused to
the set of circuit board pads. Such a system is well-suited for lead-free solder.

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